

Hiner-pack® MHWJ Canister 150 mm

Engineered for safe handling of delicate wafers during shipping and storage

Wafer jars are an efficient semiconductor wafer storage container for multiple wafers, offering cost-effective protection for non-sensitive wafer types. Molded from high-quality natural polypropylene, they feature a tight-fitting lid to prevent accidental openings. Inside, wafers are safeguarded by interleaf separators, cushioned foam disks, and lined foam walls, minimizing shock, vibration, and contact damage. Standard sizes include 150mm and 200mm, with custom sizing available. Color options—clear, white, or black—allow for inspection visibility or ESD control. Stackable for space efficiency and reusable for waste reduction, these jars are widely used in cleanroom wafer storage, inter-fab shipping, and production environments requiring dependable contamination prevention.

SPECIFICATIONS

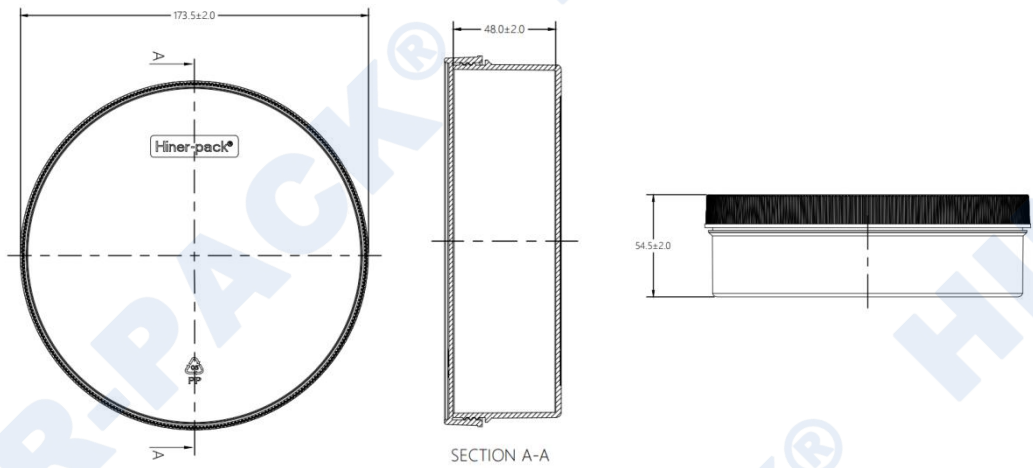
- 173.5 mm L × 173.5 mm W × 54.5 mm H (6.83" × 6.83" × 2.15")
- Maximum load capacity is 25 pieces
- Sold in full case quantity (81)

FEATURES & BENEFITS

- Interleaf separators prevent direct wafer surface contact
- Foam liners and cushion disks absorb shocks and vibration
- The bottom and the top cover are designed to facilitate the operator to open and ensure safety during transportation



DIMENSION



BASIC INFORMATION

Part Number	Collocation Reference	Wafer Size
MHWJ-6/25-160/48-NP	Bottom+Foam+Interleaf+Liner+Top	150 mm

REFERENCE ILLUSTRATION



The above illustration is for reference only. Please refer to the actual product for accuracy.

TECHNICAL DATA

PROPERTY	TEST METHOD	RATED VALUES
Density	ISO 1183	0.9 g/cm ³
Melt Index	ISO 1133	15 g/10min
Melting Point	DSC	146°C
Distortion Temperature	ISO 75	95°C
Vicat softening temperature	ISO 306	125°C
Tensile Strength at Yield	ISO 527	280 kg/m ²
Tensile Elongation at Break	ISO 527	300 %
Rockwell hardness R scale	ISO 2039	98
Tensile Strain at Break	ISO 527-2 (50mm/min)	10 %
Flexural Modulus	ISO 178	10500 kg/m ²
Flow Shrinkage	FPC Method	1.3~1.7 %
LZOD Impact Strength	ISO 180 23°C -20°C	6 kg.cm/cm --- notch

The information on technical data included in this document is based on our experience to date, and we believe it to be reliable. Data is obtained from specimens molded under controlled conditions from representative samples of the compound described. Properties may be affected by the molding techniques and by the size and shape of the item molded. We cannot guarantee favorable results and no assurances can be implied that all molded articles have the sample properties as those listed.



Hiner-pack®

Corporate Headquarters

Bldg A11, Zone D, West Industrial Zone,
Minzhu Comm., Shajing St., Bao'an,
Shenzhen, Guangdong, China

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Customer Service

Tel +86 755 2322 9236
Fax +86 755 2996 0455
Work Time 08:00 - 18:00 (Beijing Time/UTC+8)

www.waferboxes.com